

# FMV13N60ES

**FUJI POWER MOSFET** 

# Super FAP-E<sup>3S</sup> series

## **N-CHANNEL SILICON POWER MOSFET**

#### ■ Features

Maintains both low power loss and low noise Lower R<sub>DS</sub>(on) characteristic More controllable switching dv/dt by gate resistance Smaller V<sub>GS</sub> ringing waveform during switching Narrow band of the gate threshold voltage (4.2±0.5V) High avalanche durability

## Applications

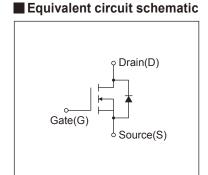
Switching regulators UPS (Uninterruptible Power Supply) DC-DC converters

# Maximum Ratings and Characteristics

# ● Absolute Maximum Ratings at Tc=25°C (unless otherwise specified)

# TO-220F(SLS)

■ Outline Drawings [mm]



Description	Symbol	Characteristics	Unit	Remarks
Duain Course Voltage	V <sub>DS</sub>	600	V	
Drain-Source Voltage	V <sub>DSX</sub>	600	V	V <sub>GS</sub> = -30V
Continuous Drain Current	ID	±13	Α	
Pulsed Drain Current	IDP	±52	А	
Gate-Source Voltage	V <sub>GS</sub>	±30	V	
Repetitive and Non-Repetitive Maximum AvalancheCurrent	IAR	13	А	Note*1
Non-Repetitive Maximum Avalanche Energy	Eas	471.5	mJ	Note*2
Repetitive Maximum Avalanche Energy	Ear	8	mJ	Note*3
Peak Diode Recovery dV/dt	dV/dt	4.7	kV/μs	Note*4
Peak Diode Recovery -di/dt	-di/dt	100	A/µs	Note*5
Mayimum Bawar Biosination	P₀	2.16	W	Ta=25°C
Maximum Power Dissipation		80	VV	Tc=25°C
Oneveting and Stavens Temperature vanue	Tch	150	°C	
Operating and Storage Temperature range	Tstg	-55 to + 150	°C	
Isolation Voltage	Viso	2	kVrms	t = 60sec, f = 60Hz

#### ● Electrical Characteristics at Tc=25°C (unless otherwise specified)

Description	Symbol	Conditions		min.	typ.	max.	Unit
Drain-Source Breakdown Voltage	BVDSS	I <sub>D</sub> =250μA, V <sub>GS</sub> =0V		600	-	-	V
Gate Threshold Voltage	V <sub>GS</sub> (th)	I <sub>D</sub> =250µA, V <sub>DS</sub> =V <sub>GS</sub>	I <sub>D</sub> =250µA, V <sub>DS</sub> =V <sub>GS</sub>		4.2	4.7	V
Zero Gate Voltage Drain Current		V <sub>DS</sub> =600V, V <sub>GS</sub> =0V	T <sub>ch</sub> =25°C	-	-	25	μА
	IDSS	V <sub>DS</sub> =480V, V <sub>GS</sub> =0V	T <sub>ch</sub> =125°C	-	-	250	
Gate-Source Leakage Current	Igss	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V		10	100	nA
Drain-Source On-State Resistance	R <sub>DS</sub> (on)	I <sub>D</sub> =6.5A, V <sub>GS</sub> =10V		-	0.50	0.58	Ω
Forward Transconductance	<b>g</b> fs	I <sub>D</sub> =6.5A, V <sub>DS</sub> =25V		5	10	-	S
Input Capacitance	Ciss	V <sub>DS</sub> =25V		-	1700	2550	pF
Output Capacitance	Coss	V <sub>GS</sub> =0V	V <sub>GS</sub> =0V		190	285	
Reverse Transfer Capacitance	Crss	f=1MHz	-	10	15		
Turn-On Time	td(on)	V <sub>cc</sub> =300V		-	38	57	
tr		V <sub>GS</sub> =10V		-	24	36	ns
Turn-Off Time	td(off)	I <sub>D</sub> =6.5A   R <sub>G</sub> =18Ω		-	86	129	115
	tf			-	16	24	
Total Gate Charge	Q <sub>G</sub>	14 00014			48	72	nC
Gate-Source Charge	Qss	- V₀c=300V - I₀=13A - V₀s=10V		-	16	24	
Gate-Drain Charge	Q <sub>GD</sub>			-	16	24	
Gate-Drain Crossover Charge	Qsw			-	7	10.5	
Avalanche Capability	lav	L=2.36mH, Tch=25°C	L=2.36mH, Tch=25°C		-	-	Α
Diode Forward On-Voltage	V <sub>SD</sub>	I <sub>F</sub> =13A, V <sub>GS</sub> =0V, T <sub>ch</sub> =25°C		-	0.90	1.08	V
Reverse Recovery Time	trr	I <sub>F</sub> =13A, V <sub>GS</sub> =0V		-	0.7	-	μS
Reverse Recovery Charge	Qrr	-di/dt=100A/µs, Tch=25°C		-	8	-	μC

#### Thermal Characteristics

Description	Symbol	Test Conditions	min.	typ.	max.	Unit
Thermal resistance	Rth (ch-c)	Channel to case			1.560	°C/W
	Rth (ch-a)	Channel to ambient			58.0	°C/W

Note \*1 : Tch≤150°C

Note \*2: Stating Tch=25°C, Ias=6A, L=24.0mH, Vcc=60V, R<sub>G</sub>=50Ω

Eas limited by maximum channel temperature and avalanche current.

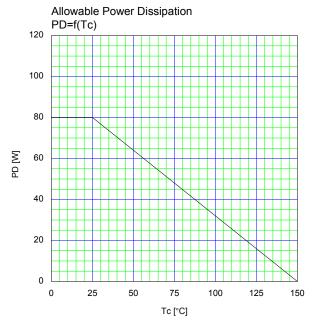
See to 'Avalanche Energy' graph.

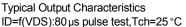
Note  $^{\star}3$  : Repetitive rating : Pulse width limited by maximum channel temperature

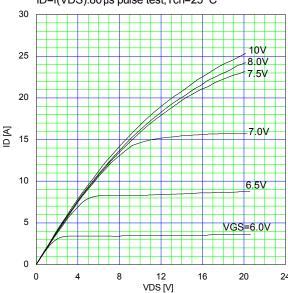
See to the 'Transient Themal impeadance' graph.

Note \*4 : I₅≤-I₀, -di/dt=100A/μ₅, Vcc≤BV₀ss, Tch≤150°C.

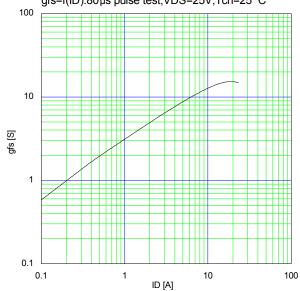
Note \*5 : I₅≤-I₀, dv/dt=4.7kV/μ₅, Vcc≤BV₀ss, Tch≤150°C.



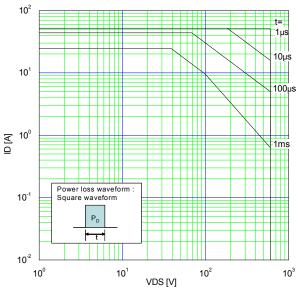




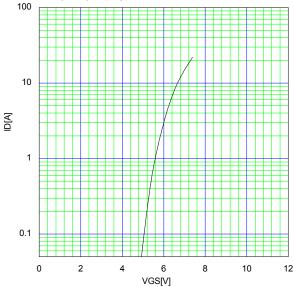
Typical Transconductance gfs=f(ID):80 µs pulse test,VDS=25V,Tch=25 °C



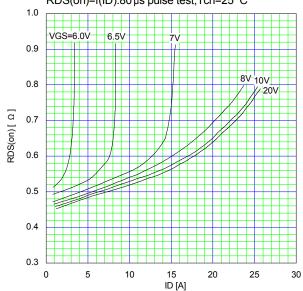
Safe Operating Area I<sub>D</sub>=f(V<sub>DS</sub>):Duty=0(Single pulse),Tc=25 °c

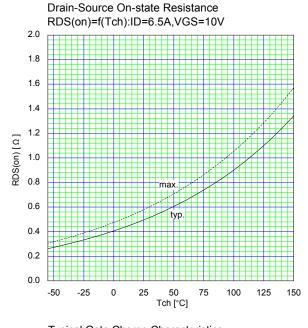


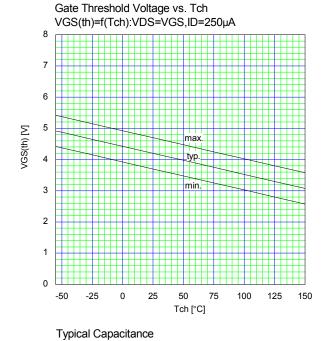
Typical Transfer Characteristic ID=f(VGS):80  $\mu$ s pulse test,VDS=25V,Tch=25  $^{\circ}$ C

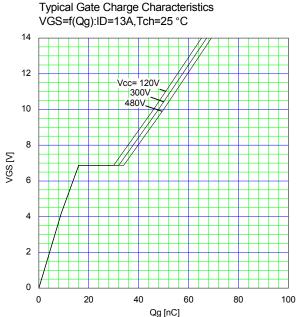


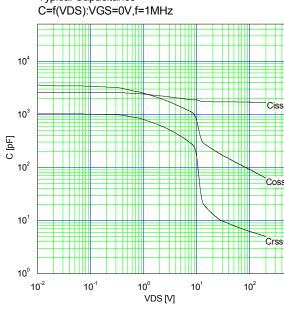
Typical Drain-Source on-state Resistance RDS(on)=f(ID):80 µs pulse test,Tch=25 °C

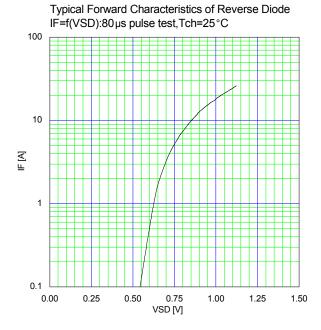


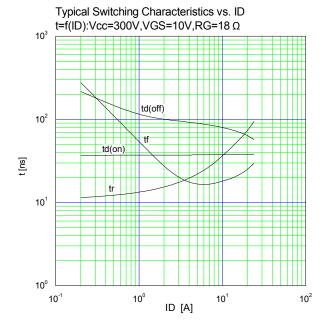


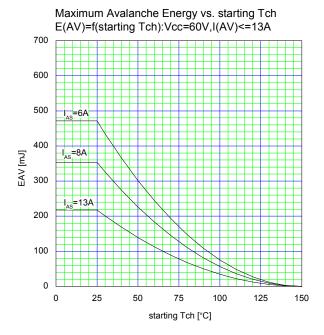


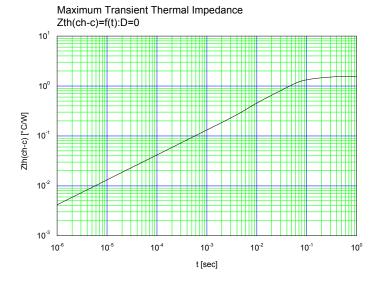












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